

MODEL GWS-300M

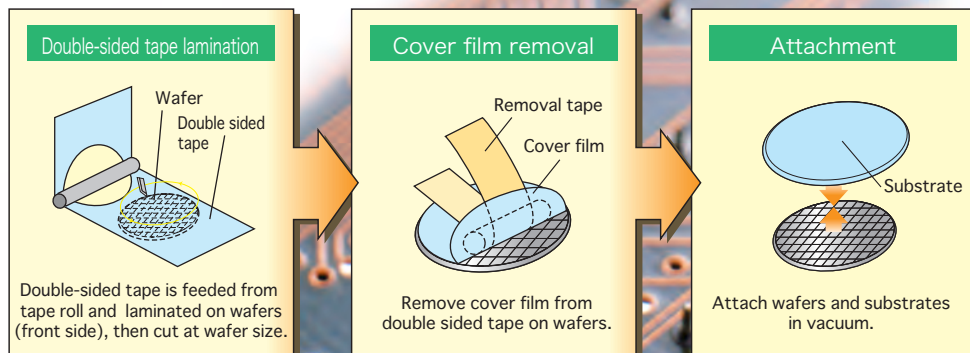
WAFER/SUBSTRATE ATTACHING MACHINE

Outline

This machine laminates double-sided tape onto wafers, remove cover film on it, and attaches wafers and substrates.

Lamination of wafer and double-sided tape & attachment of wafers and substrates is made in Takatori unique vacuum chamber.

So the laminating without air bubbles and with uniform attaching pressure is available.



8 · 12 inch
Wafers



Specification	GWS-300M
Throughput	30~40wafer/h
Wafer Size	8 inch, 12 inch
Dimensions	D2,400 × W2,400 × H1,800mm
Weight	Approx 1,200kg

System appearance and specifications are subject to change without prior notice from the supplier.

313-1 Shindo-cho, Kashihara City, Nara, Japan 634-8580

Phone: +81(0)744-24-7670

Fax: +81(0)744-24-8352

URL <http://www.takatori-g.co.jp> E-mail info@takatori-g.co.jp